

## FEATURES AND SPECIFICATIONS

### Features and Benefits

- Sizes 10 to 60 circuits
- Selective Gold- and Tin-plated versions

### Reference Information

Packaging: Tray  
 UL File No.: E29179-E  
 Mates With: [5320-NA](#) and [5320-NB](#)  
 Designed In: Millimeters

### Electrical

Current: 1.0A  
 Contact Resistance: 20mΩ max.  
 Dielectric Withstanding Voltage: 500V AC  
 Insulation Resistance: 1000 MΩ min.

### Physical

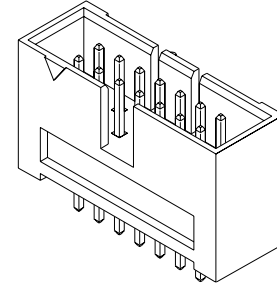
Housing: Black glass-filled polyester, UL 94V-0  
 Contact: Brass  
 Contact Pin: 0.635mm (.025") square  
 Plating: See Table  
 Operating Temperature: -40 to +105°C

**molex**® **2.54mm (.100") Pitch**  
**QF 50™**

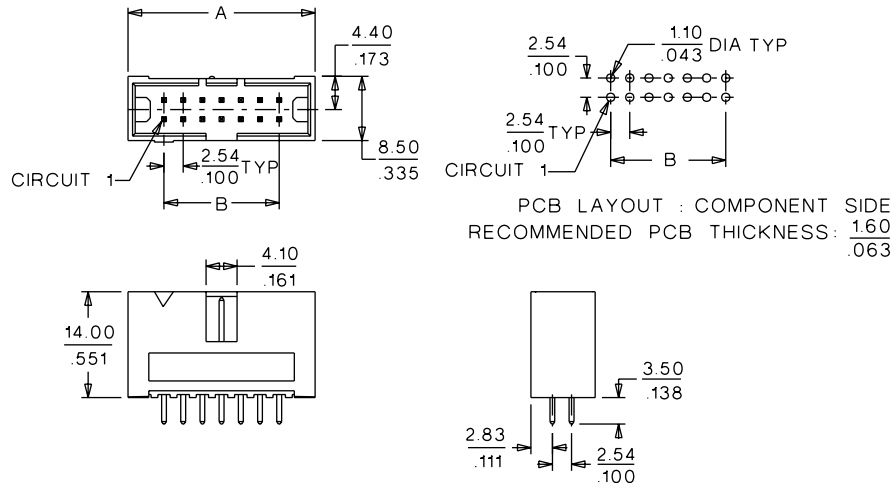
**Shrouded Header**

**5332**

**Vertical, Dual Row**  
**Single Polarization**



## CATALOG DRAWING (FOR REFERENCE ONLY)



## ORDERING INFORMATION AND DIMENSIONS

Circuits	Order No.		Dimension	
	Plating NGS1	Plating NT2	A	B
10	39-26-7105	39-28-5101	19.66 (.774)	10.16 (.400)
14	39-26-7145	39-28-5141	24.74 (.974)	15.24 (.600)
16	39-26-7165	39-28-5161	27.28 (1.074)	17.78 (.700)
20	39-26-7205	39-28-5201	32.36 (1.274)	22.86 (.900)
26	39-26-7265	39-28-5261	39.98 (1.574)	30.48 (1.200)
30	39-26-7305	39-28-5301	45.06 (1.774)	35.56 (1.400)
34	39-26-7345	39-28-5341	50.14 (1.974)	40.64 (1.600)
40	39-26-7405		57.76 (2.274)	48.26 (1.900)
50	39-26-7505		70.46 (2.774)	60.96 (2.400)
60	39-26-7605		83.16 (3.274)	73.66 (2.900)

Plating NGS1: 39μ" (1μm) min. Nickel underplate. Contact area: 4μ" (0.1μm) min. Gold.  
 Solder area: 3μm min. Tin/Lead.

Plating NT2: 35μ" (0.9μm) min. Tin overall